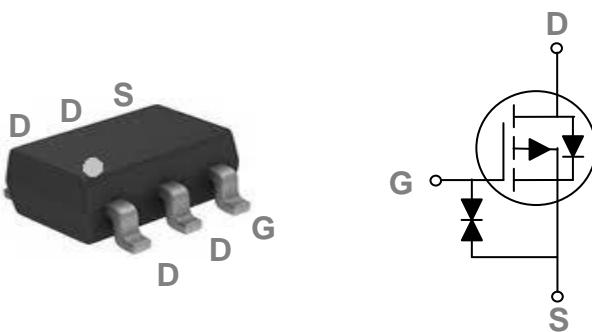


General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-6L Pin Configuration



BVDSS	RDSON	ID
-20V	33mΩ	-5.8A

Features

- -20V,-5.8A, RDS(ON) =33mΩ@VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Networking

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-5.8	A
I_D	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	-3.7	A
I_{DM}	Drain Current – Pulsed ¹	-23.2	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	1.56	W
P_D	Power Dissipation – Derate above 25°C	0.012	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	---	-0.02	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 10	μA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4\text{A}$	---	28	33	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_{\text{D}}=-3\text{A}$	---	37	45	
		$V_{\text{GS}}=-1.8\text{V}$, $I_{\text{D}}=-2\text{A}$	---	49	65	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-0.3	-0.6	-1	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	2	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{S}}=-3\text{A}$	---	8.4	---	S

Dynamic and switching Characteristics

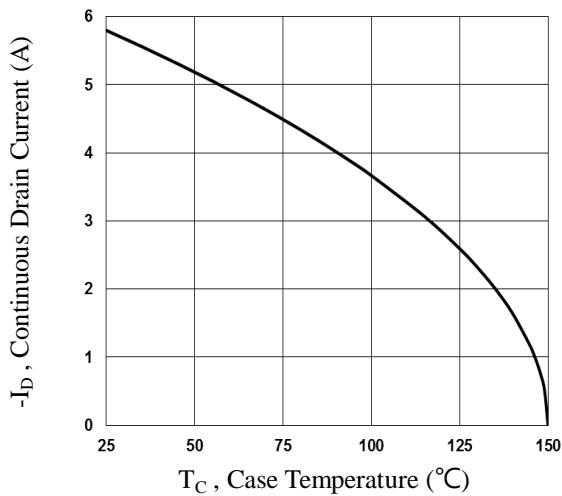
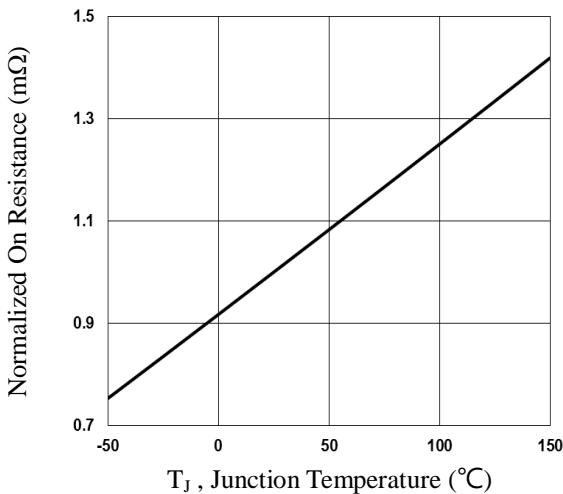
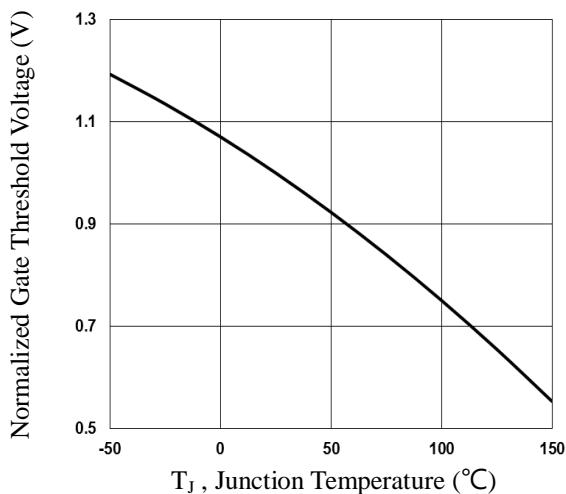
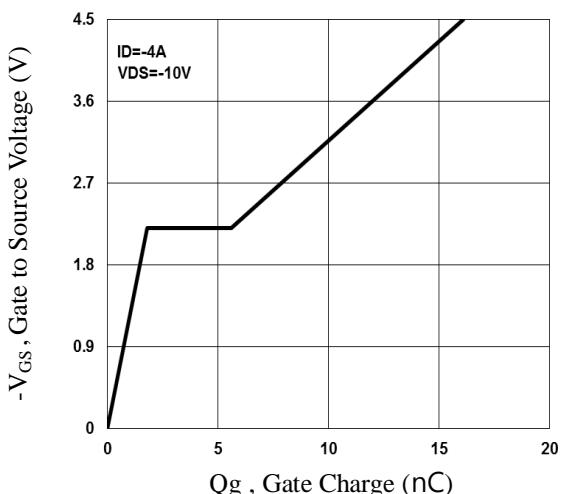
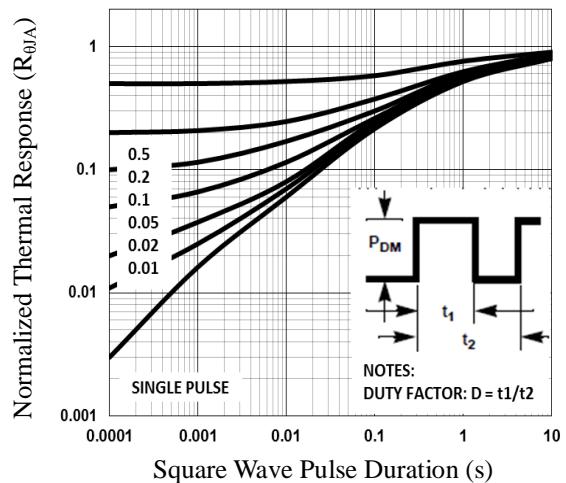
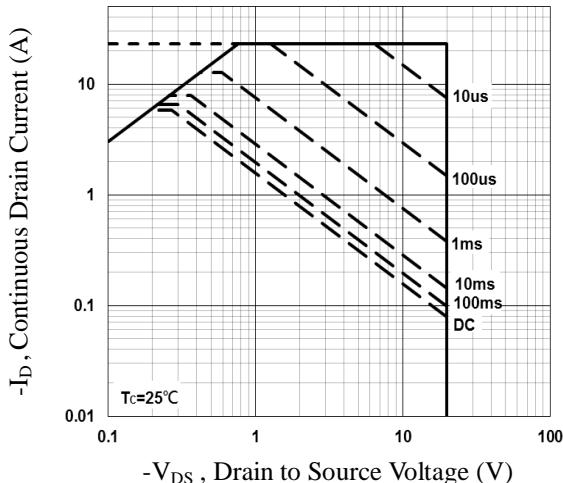
Q_g	Total Gate Charge ^{2,3}	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-4\text{A}$	---	16.1	25	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.8	3	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	3.8	7	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_{\text{G}}=25\Omega$ $I_{\text{D}}=-1\text{A}$	---	8.2	16	nS
T_r	Rise Time ^{2,3}		---	30	57	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	71.1	135	
T_f	Fall Time ^{2,3}		---	19.8	38	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	1440	2100	pF
C_{oss}	Output Capacitance		---	155	230	
C_{rss}	Reverse Transfer Capacitance		---	115	170	

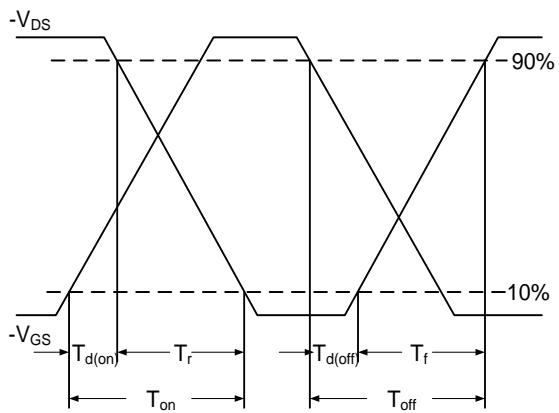
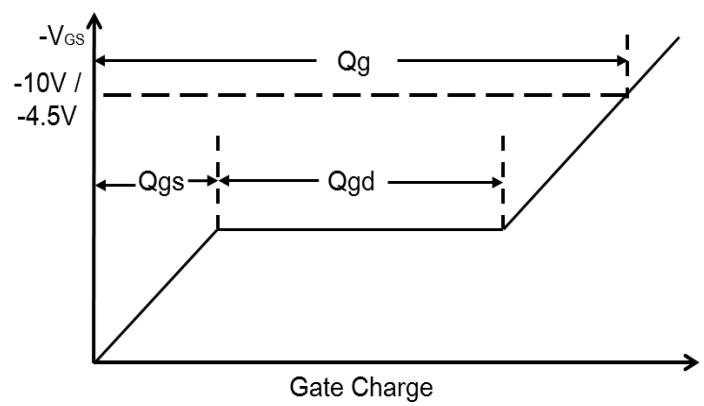
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-5.8	A
I_{SM}	Pulsed Source Current		---	---	-23.2	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

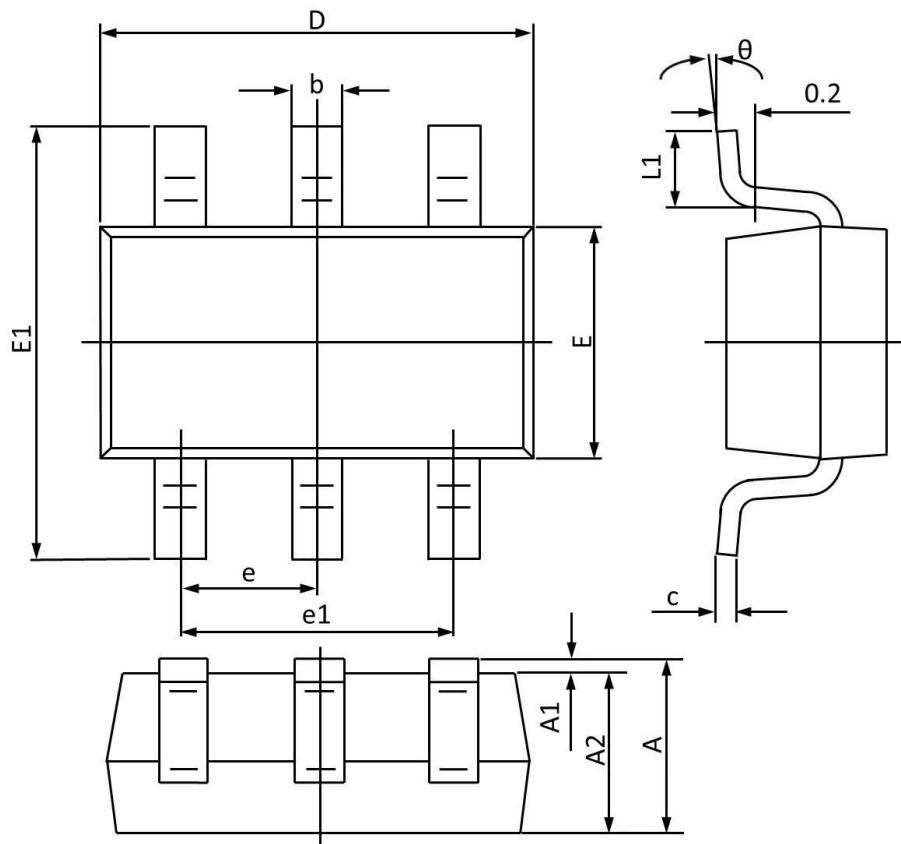
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized RDSON vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

SOT23-6L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.450	-	0.057	-
A1	0.100	0.000	0.004	0.000
A2	1.300	1.050	0.051	0.041
b	0.500	0.300	0.020	0.012
c	0.200	0.100	0.008	0.004
D	3.100	2.700	0.122	0.106
E	1.800	1.400	0.071	0.055
E1	3.000	2.600	0.118	0.102
e	0.95BSC		0.037BSC	
e1	2.000	1.800	0.079	0.071
L1	0.600	0.300	0.024	0.012
θ	10°	0°	10°	0°